

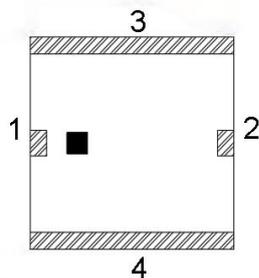
Features

- Multilayer monolithic construction yields high reliability
- Low insertion loss and small size SMD chip design
- Can simplify your complex tuning and circuit design
- LTCC process

Specifications

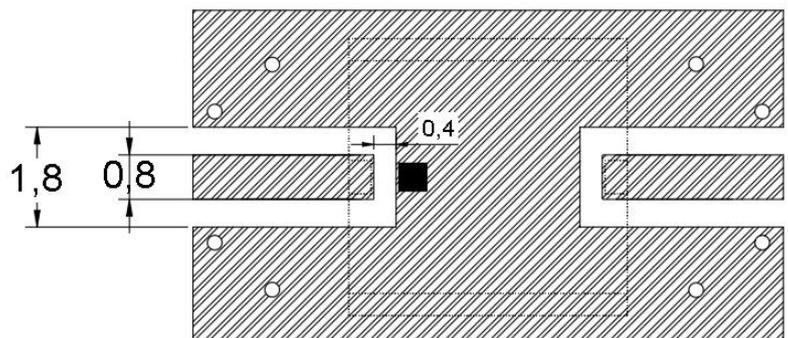
NO.	Parameter		SPEC
1	Frequency (MHz)		300-2000
2	Insertion Loss (dB) @25°C	300-2000MHz	≤1.5
3	Ripple (dB)	300-2000MHz	≤0.5
4	Attenuation(dBc)	10MHz~230MHz	≥35
		2400MHz~3400MHz	≥35
5	VSWR(In BW)		≤1.6
6	Phase Consistency		±5° (8 pcs per group)
7	Amplitude Consistency		0.1dB
8	Group Latency Consistency		<0.5nS
9	In/Output Impedance (Ω)		50
Operating & Storage Condition (Component)			
Operation Temperature Range: -40°C ~ +85°C			
Storage Temperature Range: -40°C~ +85°C			
Storage Condition before Soldering (Included packaging material)			
Storage Temperature Range: +5 ~ +40 °C			
Humidity: 30 to 70% relative humidity			

Construction



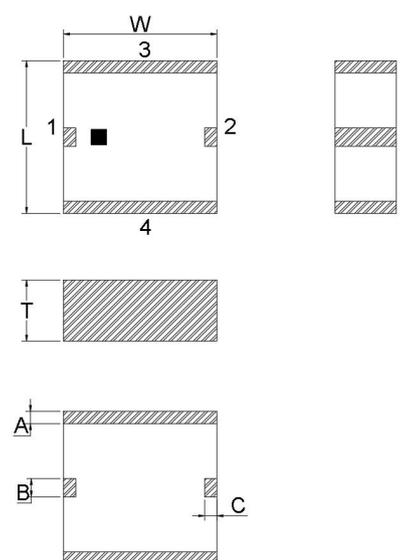
PIN	Connection
1	Input Port
2	Output Port
3	GND
4	GND

Mounting Considerations

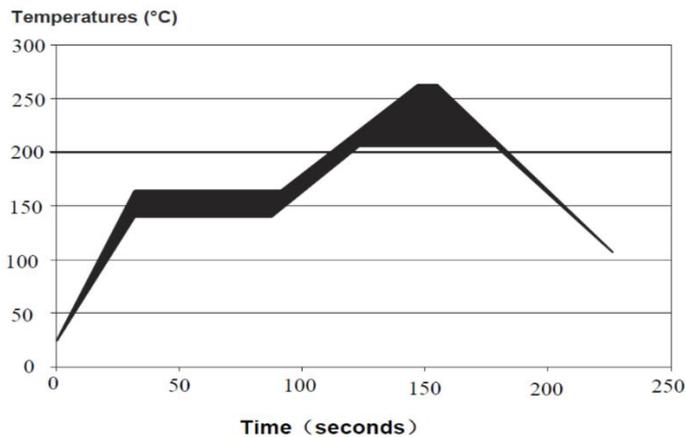


Unit: mm

Dimensions

Figure	Symbol	Dimension (mm)
	L	5.00± 0.20
	W	5.00± 0.20
	T	2.00± 0.20
	A	0.40± 0.10
	B	0.60 ± 0.10
	C	0.40± 0.10

Solder Reflow Standard Conditioning



Storage Conditions

Temperature : +5 to +30 °C

Humidity : 20 to 70% RH

Term of storage : Within 12 months (After the delivery) *

Baking : Unnecessary

* After peeling off cover tape, do not keep exposing the products to the open air. For the products stored longer than 12 months, confirm their terminals and solderability before use.